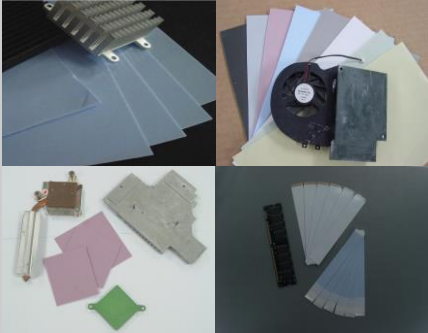


THERMAL CONDUCTIVE GAP FILLER 1.2 W/m-K

Features and Benefits

- 1.2W/m-K thermal conductivity
- Moderate compressibility
- Cost effective
- Electrically isolating
- RoHS compliant
- Halogen-free



Typical Applications

- High speed mass storage devices
- RDRAM memory modules
- Heat pipe assemblies
- Cooling components to the chassis, frame or other types of heat spreader
- Motor controls
- Wireless communication hardware

Optional Configurations

- Can be die-cut into specific dimensions

E-Fill 8100 is a gap filling material suitable for cost sensitive applications.

It is electrically non-conductive and offers moderate thermal conductivity and compressibility.

The proprietary formulation of E-Fill 8100 is RoHS compliant and halogen-free, providing extra reassurance in applications where hazardous substances are forbidden.

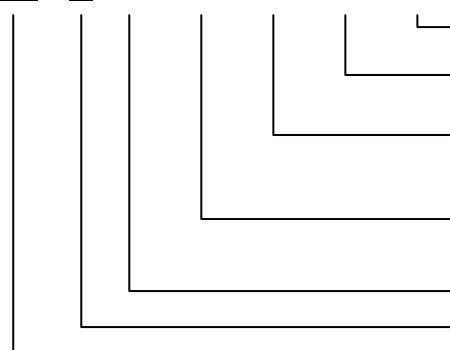
Properties	Typical Data	Test Method
Construction & Composition	Soft silicone elastomer	—
Color	Blue	Visual
Thickness Range /inch (mm)	0.01~0.40" (0.254~10.16) in 0.01" (0.254) increments	—
Standard Sheet Size	12" x 16"	—
Density /g.cm ⁻³	1.8	—
Hardness /Shore 00	60	ASTM D2240
UL Flammability Rating	UL94 V0	E109346
Temperature Range /°C	-40~200°C	—
Thermal Conductivity W.m ⁻¹ .K ⁻¹	1.2	ASTM D5470 (modified)
Breakdown Voltage /V	>6000 (Thickness ≤ 0.05") >10000 (Thickness ≥ 0.06")	ASTM D149
Volume Resistivity /ohm.cm	3.0 x 10 ¹³	ASTM D257
Dielectric Constant @ 1MHz	5.0	ASTM D150
Shelf Life	24 months	—

Please contact us for other special requirements

Carrier Treatment	Criteria
Fiber Glass (FG)	Compulsory for ≤ 0.02" (0.5mm)
Rubberized Cloth (RC)	Not Recommended
Pressure Sensitive Adhesive (PSA)	Optional to all thickness
Detachable Adhesive (DA)	Not Recommended
Aluminum Foil (AL)	Not Recommended
Kapton (PI)	Not Recommended
Talc treatment (DAT)	Not Recommended

Product Code and Descriptions

E-Fill 81 XX - XX - XX - XX - XX



- Dimensions**
SS = Standard sheet size
CD = Custom dimensions
- Release Liner**
ST = Standard
OT = Other
- PSA**
A1 = One side
A2 = Both sides
OT = Other
- Carrier**
FG = Fiberglass
RC = Rubber
CB = Combination
OT = Other
- Thickness (mil)**
00 = Custom thickness
40 = 40mil
- 81 = 8100 Series**
E-Fill = E-Fill gap filling material

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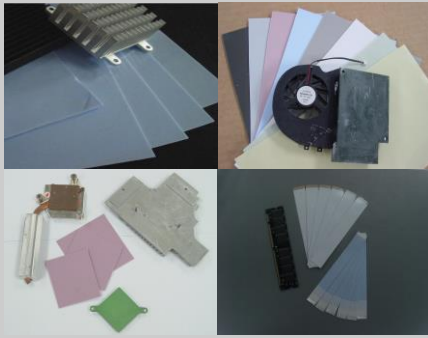
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产品特点

- 导热率 1.2W/m-K
- 中等压缩比
- 低成本
- 电绝缘
- 符合 RoHS 规格
- 无卤素



一般应用

- 高速大容量存储设备
- RDRAM 记忆模组
- 热管组件
- 底盘，框架或其他散热组件
- 电机控制器
- 无线通信硬件

其他配置

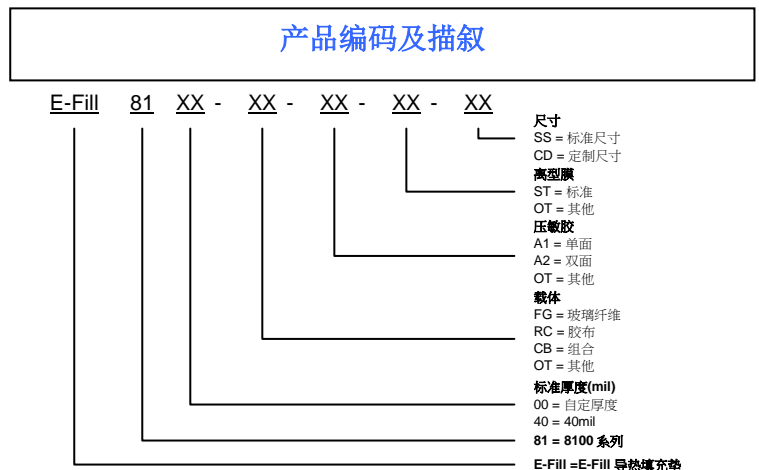
- 可模切成特定尺寸

E-Fill 8100 是导热填充垫，专门应用于对成本敏感的项目上，E-Fill 8100 对电绝缘而且提供中等导热率及压缩比。

E-Fill 8100 独有的配方不单指符合 RoHS 规格而且更达到无卤素要求，令客户在使用时对于有害物质的控制更有信心。

一般特性	E-Fill 8100 系列	测试方法
结构及主要成分	硅树脂弹性体	—
颜色	多种颜色	目测
厚度 /inch (mm)	0.01~0.40" (0.254~10.16) 以 0.01" (0.254)为基本增量单位	—
标准片材尺寸	12" x 16"	—
密度 /g.cm ⁻³	1.76	—
硬度 /Shore 00	60	ASTM D2240
UL 燃烧等级	UL94 V0	E109346
使用温度 /°C	-40~200°C	—
导热率 W.m ⁻¹ .K ⁻¹	1.2	ASTM D5470 (modified)
击穿电压/V	>6000 (厚度 ≤ 0.05") >10000 (厚度 ≥ 0.06")	ASTM D149
体积电阻率 /ohm.cm	3.0 x 10 ¹³	ASTM D257
介电常数@ 1MHz	5.0	ASTM D150
有效期	24 months	—
如对产品有特殊要求，请联络我们		

载体	标准
玻璃纤维 (FG)	厚度 ≤ 0.02" (0.5mm) 必须使用
胶布 (RC)	不建议使用
压敏胶 (PSA)	可供任何厚度使用
不粘胶 (DA)	不建议使用
铝箔 (AL)	不建议使用
聚酰亚胺膜 (PI)	不建议使用
滑石粉处理 (DAT)	不建议使用

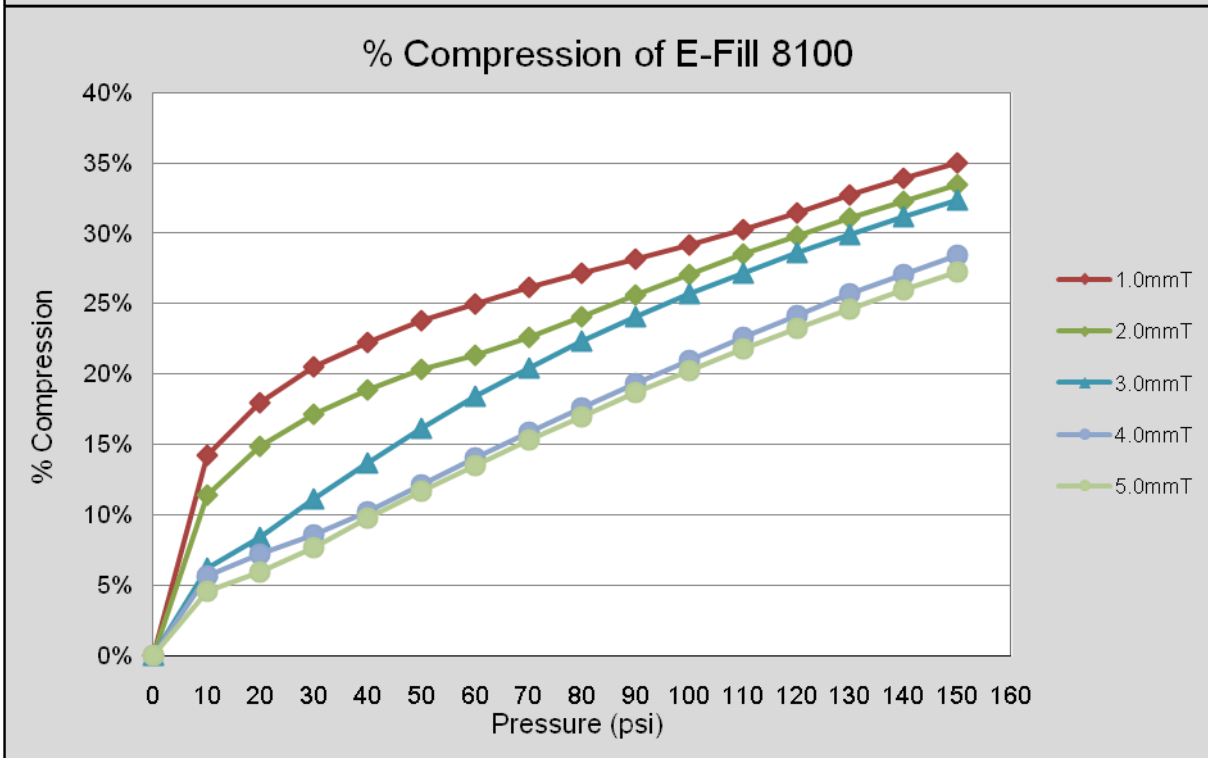
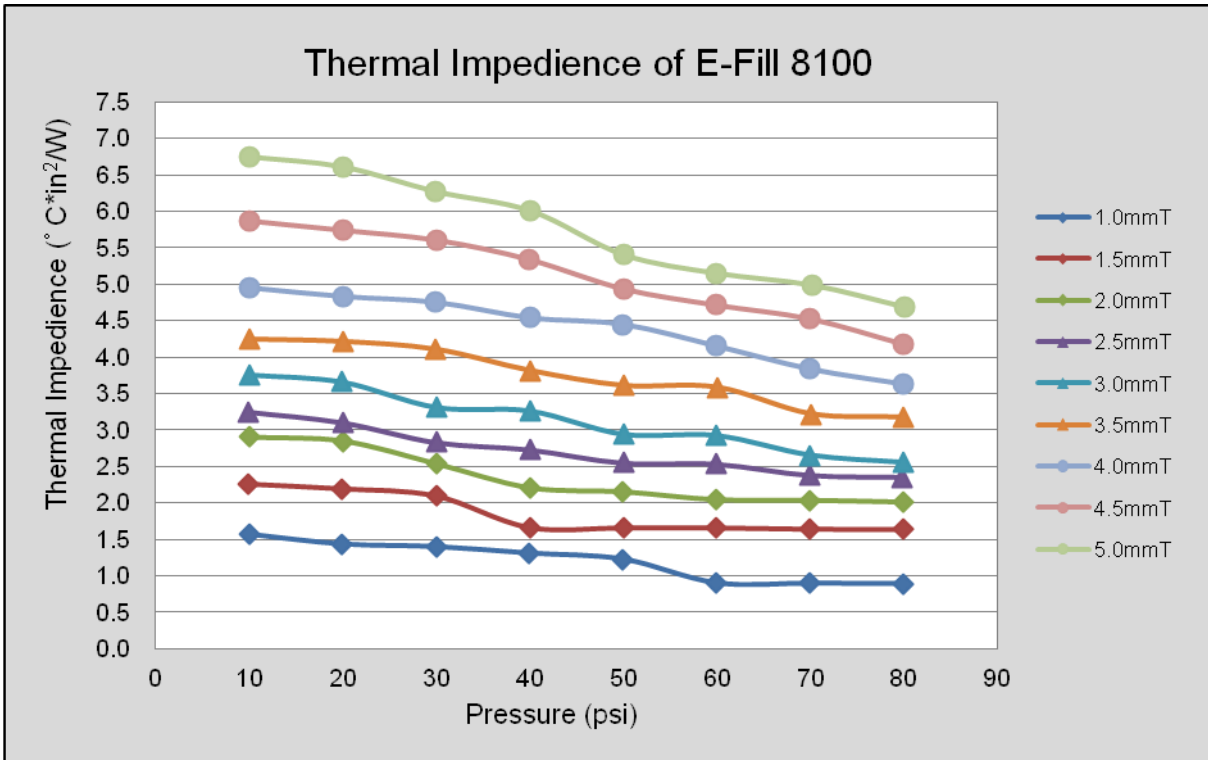


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